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Universal Evaluation Board for Dual High Speed Op Amps Offered in 8-Lead 3 mm × 3 mm LFCSP

FEATURES

Enables quick breadboarding/prototyping
User defined circuit configuration
Edge mounted SMA connector provisions
Easy connection to test equipment and other circuits

GENERAL DESCRIPTION

The Analog Devices, Inc., dual LFCSP universal evaluation board is designed to help users evaluate dual high speed op amps offered in 8-lead, 3 mm × 3 mm lead frame chip scale packages (LFCSP). The dual LFCSP board is a bare board (that is, there are no components soldered to the board) that enables users to quickly prototype a variety of dual op amp circuits, which minimizes risk and reduces time to market. Figure 1 and Figure 2 show the bare evaluation board, component side and solder side, respectively.

The evaluation board is a 6-layer printed circuit board (PCB) that accepts SMA edge mounted connectors on the inputs and outputs for efficient connection to test equipment or other circuitry. The ground plane and component placement are designed to minimize parasitic inductances and capacitances. The evaluation board components are primarily SMT 0603 case size, with the exception of the electrolytic bypass capacitors (C1 and C2), which are 1206 case size.

Figure 3 shows the evaluation board schematic. Figure 4 and Figure 5 show the assembly drawing and the layout pattern of the component side, respectively. The bill of materials is listed in Table 1.

EVALUATION BOARD LAYOUT PATTERN

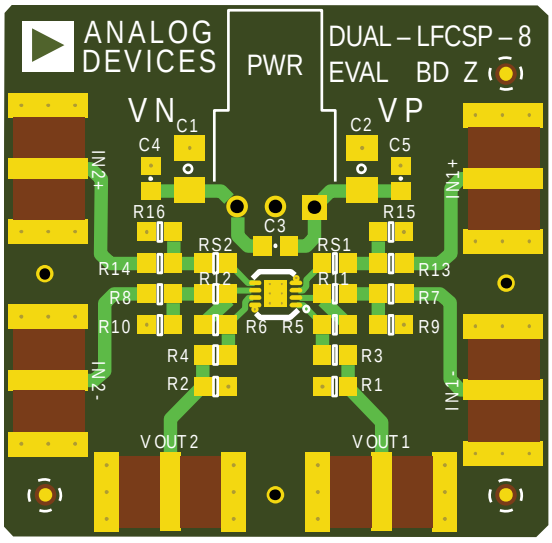

Figure 1. Evaluation Board, Component Side

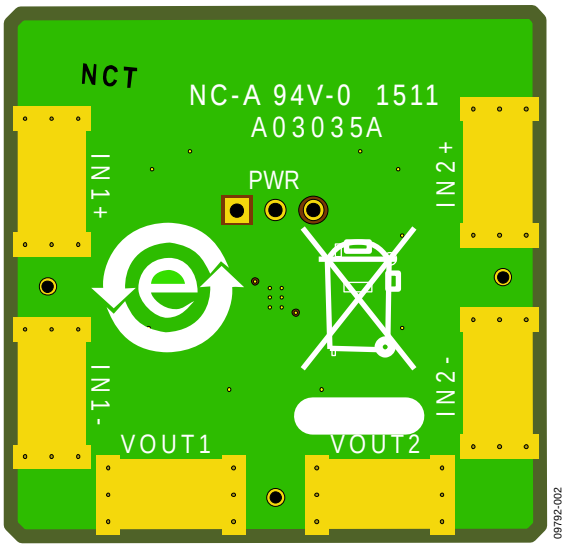

Figure 2. Evaluation Board, Solder Side

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REVISION HISTORY

6/11—Revision 0: Initial Version

EVALUATION BOARD SCHEMATIC AND ARTWORK

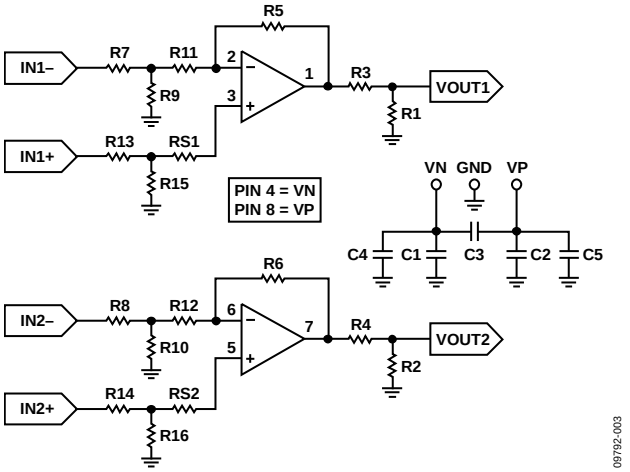

Figure 3. Dual LFCSP Evaluation Board Schematic

EVALUATION BOARD ASSEMBLY DRAWINGS AND LAYOUT PATTERNS

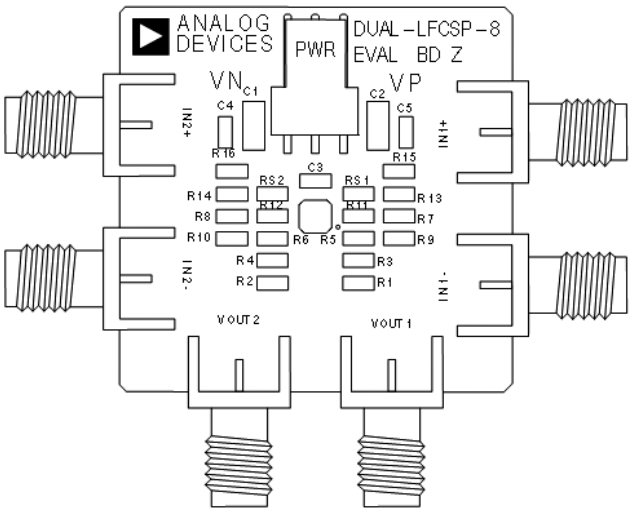

Figure 4. Component Side Assembly Drawing

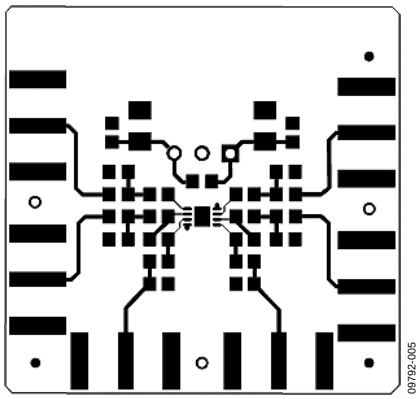

Figure 5. Component Side Layout Pattern

ORDERING INFORMATION

BILL OF MATERIALS

Table 1.

Quantity	Reference Designator	Description	Package
3	VP, VN, PWR	Test point	TP
2	C1, C2	10 µF capacitor	1206
3	C3, C4, C5	Capacitor, user defined	0603
1	DUT	See data sheet packaging information	8-lead LFCSP
6	IN1+, IN1−, IN2+, IN2−, VOUT1, VOUT2	SMA/SMT	SMA/SMT
18	R1 to R16, RS1, RS2	Resistor, user defined	R0603

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